

MODEL: HSB41-303014P | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- push pins
- aluminum alloy
- black anodized finish



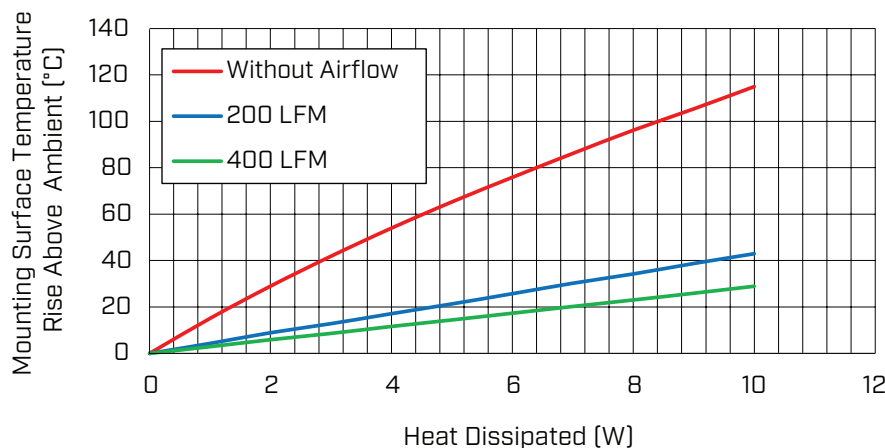
MODEL

	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB40-252510P	12.63	15.1	4.3	2.9	5.94

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	15.1	4.3	2.9
2	29.0	8.9	5.9
3	41.9	12.8	8.6
4	54.0	17.1	11.6
5	65.3	21.3	14.4
6	75.9	25.7	17.3
7	86.2	30.2	20.2
8	96.2	34.2	23.0
9	105.4	38.7	25.9
10	115.0	42.9	28.9

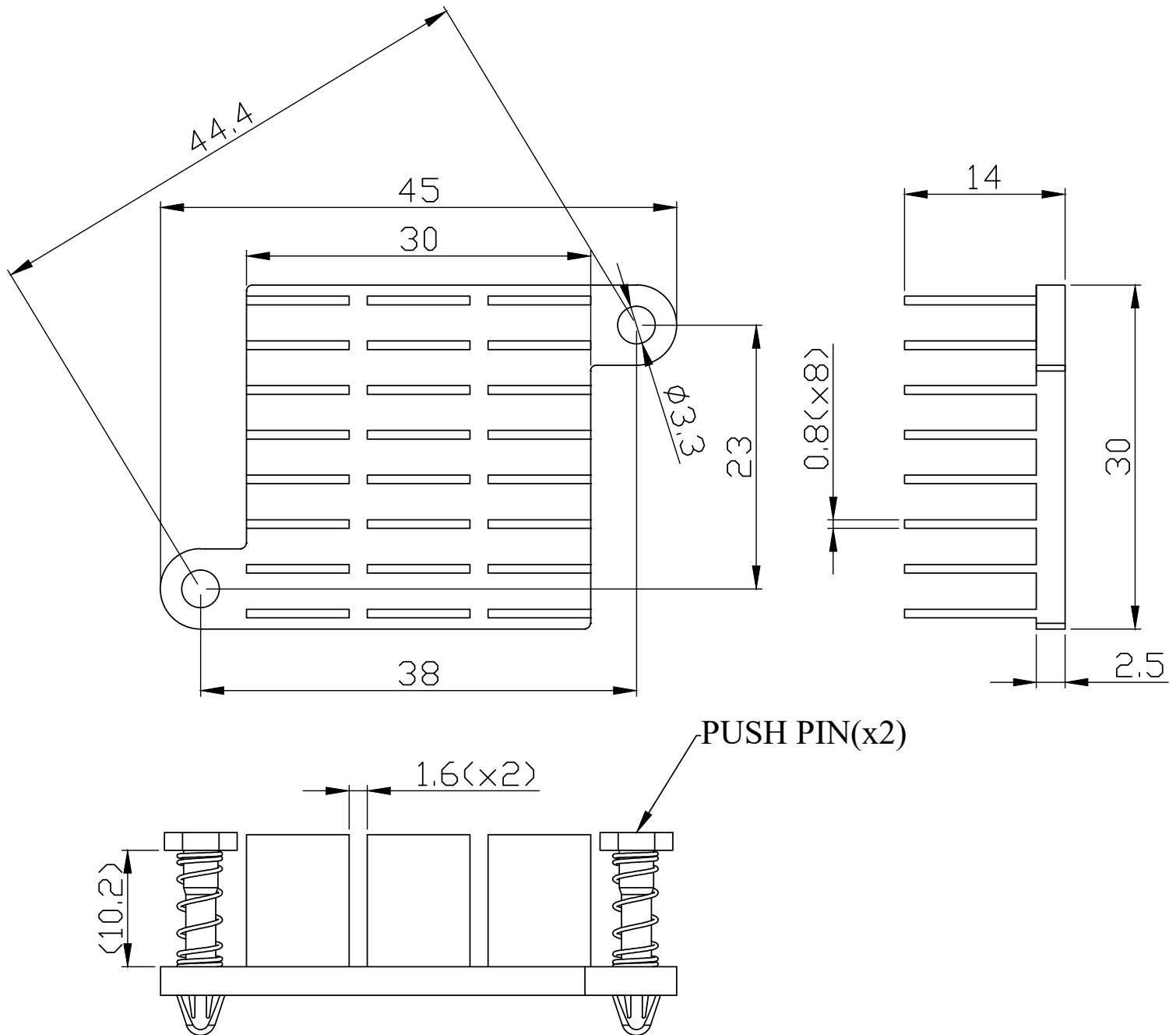


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	nylon 66
SPRING	spring steel, zinc plated
WEIGHT	15 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



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